



## CONTINUOUS IMPROVEMENT

Continuous Flow Manufacturing  
Mistake Proofing Techniques  
High Performance Work Teams  
Six Sigma Techniques

Quality Teams  
Visual Factory  
Performance Board

## 6 "S"

Sort – Straighten – Shine – Standardize – Sustain - Safety

## SERVICES

Lean Manufacturing  
Flexible Circuit Assembly  
Repair Services  
Turnkey-Consignment  
Chassis & System Integration  
Customer Supported Layout & Design

Quick Turn Prototyping  
Inspection & Testing  
Kanban Services  
High Mix Production  
Wire & Cable Harness

## CAPABILITIES

### Surface Mount assembly equipment:

Board Size Min = 50 mm x 50 mm (2" x 2")  
Board Size Max = 508 mm x 508 mm (20" x 20")

- 2 EKRA X4 screen printers
- 2 EKRA Serio 4000 volume printers
- 2 Parmi SigmaX Blue solder paste inspection
- 2 Samsung SM481 placement systems
- 1 Samsung SM482 placement system
- 2 Samsung SM 421 placement systems
- 1 Samsung SM485 placement system
- 1 Samsung SM411 placement system
- 1 Samsung SRF70i123 reflow oven
- 2 BTU Pyramax reflow ovens (models 98 & 125)

### Ball Grid Array and Advanced SMD's

ERSA HR600/2  
BGA's (BGA placement up to 55mm<sup>2</sup> 1.0mm pitch)  
µBGA (0.5mm pitch)  
Ultrafine pitch components (0.4mm pitch)  
QFN/MLP  
LGA  
CSP  
01005 chip components  
Odd Form components  
Large Connectors (up to 72mm diag.)

### Soldering - Lead or Lead Free (RoHS)

Board Size Min = 50 mm x 50 mm (2" x 2")  
Board Size Max = 400 mm x 510 mm (16" x 20")  
4 Wave Solder Machines (Electrovert EPK, Electrovert Vectra Elite, Vitronics Soltec Delta 5, Ersa Powerflow)  
1 Seho Selectline C Soldering Machine  
Board Size Max = 500mm x 500mm (19.68" x 19.68")  
2 Ersa Smartflo 2020 Selective Soldering Machines (Max 18" x 24")

### Through-Hole assembly equipment:

Board Size Min = 50 mm x 50 mm (2" x 2")  
Board Size Max = 350 mm x 460 mm (14" x 18")  
6 Contact Systems CS-400 Component Locators

## Automated Optical Inspection

Board Size Min = 50 mm x 50 mm (2" x 2")  
Board Size Max = 510 mm x 660 mm (20" x 26")  
2 Mirtec In-Line MV-6 Omni 3D  
1 Mirtec In-Line MV-7U  
1 Mirtec In-Line MV-7xi  
2 Mirtec Desktop MV-2HTL  
15 Mega pixel downward camera with a telecentric compound lens  
10 Mega pixel side-view cameras  
Intelli-Scan Laser inspection  
(lifted lead and BGA/QFN co-planarity check)  
45mm part clearance (same for MV2-HTL)  
50mm x 50mm to 660mm x 510mm PCB capacity  
SPC data collection

## X-Ray Inspection

1 FeinFocus Yxlon Y. Cougar X-Ray Inspection station

## Automated Depaneling

1 Cencorp 1000BR – depaneling and high-capacity router

## 3D Printing

MakerBot 3D Extrusion Printer

## Laser Marking

Insignum 4000 Automatic Laser Marking System

## Cleaning

1 Technical Devices Nu/Clean 824 XLR-FB Inline Aqueous Wash Machine  
Board Size Min = n/a  
Board Size Max = 24 x 25"

## PCB Conformal Coating

1 PVA6000 Conformal Coating Machine and IR2000 Curing Oven  
Board size 600mm x 600mm (23.6" x 23.6")  
Acrylic / Urethane / Silicone / Polyurethane

## Potting/Encapsulation

Fisnar 3 Axis Dispensing Robot

## Nitrogen Generator

1 On – Site N-150 TGN Nitrogen Generator

## Circuit Board Testing

1 SPEA Flying Probe  
2 Teradyne LH In-Circuit Test Stations  
Functional testing on customer owned fixtures  
Custom Test Fixtures

## Programming

1 Data I/O 3980xpi  
1 BPM Microsystems 1610

## Inventory Control

1 Optical Control OC Scan CCX.3 component counter

## Vayo NPI 3D DFM Software

## High Voltage Soldering

## Product Identification and Traceability